

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Kenya TACHIBANA</td> <td>07/09/2009</td> </tr> <tr> <td>Masahiro WADA</td> <td>07/09/2009</td> </tr> <tr> <td>Hitoshi KAWAGUCHI</td> <td>07/13/2009</td> </tr> <tr> <td>Kensuke NAKAMURA</td> <td>07/09/2009</td> </tr> </tbody> </table>		Name	Execution Date	Kenya TACHIBANA	07/09/2009	Masahiro WADA	07/09/2009	Hitoshi KAWAGUCHI	07/13/2009	Kensuke NAKAMURA	07/09/2009
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>SUMITOMO BAKELITE CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>5-8, Higashi-Shinagawa 2-chome, Shinagawa-ku</td> </tr> <tr> <td>City:</td> <td>Tokyo</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>1400002</td> </tr> </table>		Name:	SUMITOMO BAKELITE CO., LTD.	Street Address:	5-8, Higashi-Shinagawa 2-chome, Shinagawa-ku	City:	Tokyo	State/Country:	JAPAN	Postal Code:	1400002
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CORRESPONDENCE DATA											
<p>Fax Number: (703)519-9958</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 703-519-9953</p> <p>Email: mnakai@dcpatent.com</p> <p>Correspondent Name: Masayasu Mori</p> <p>Address Line 1: 918 PRINCE STREET</p> <p>Address Line 4: Alexandria, VIRGINIA 22314</p>											
ATTORNEY DOCKET NUMBER:	01159_1027										
NAME OF SUBMITTER:	Masayasu Mori										
<p>Total Attachments: 2</p> <p>source=01159_1027_Assignment#page1.tif</p>											

OP \$40.00 12517551

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PATENT
REEL: 023334 FRAME: 0850

Attorney Docket No.: 01159_1027
Client Docket No.: PCT09059US

Patent

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we the undersigned, Kenya TACHIBANA, Masahiro WADA, Hitoshi KAWAGUCHI, and Kensuke NAKAMURA, hereby sell, assign, and transfer to SUMITOMO BAKELITE COMPANY LIMITED, a corporation of Japan, having a principal place of business at 5-8, Higashi-shinagawa 2-chome, Shinagawa-ku, Tokyo 1400002 Japan ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements that are disclosed in the application for the United States patent, entitled:

SEMICONDUCTOR PACKAGE, CORE LAYER MATERIAL, BUILDUP LAYER MATERIAL, AND SEALING RESIN COMPOSITION

- ☐ which has been executed by the undersigned concurrently herewith,
☒ which was filed on June 3, 2009 and assigned Serial No. 12/517,551

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;

agree that said Assignee may apply for and receive a patent or patents for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all assignments and powers of attorney; communicate to said Assignee, its successors, assigns, and representatives all facts known to the undersigned relating to said improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or representatives in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Attorney Docket No.: 01159_1027
Client Docket No.: PCT09059US

Patent

Each Inventor: Please Sign and Date Below:

July 9, 2009
Date

Kenya Tachibana
Name: Kenya TACHIBANA

Each Inventor: Please Sign and Date Below:

July 9, 2009
Date

Masahiro Wada
Name: Masahiro WADA

Each Inventor: Please Sign and Date Below:

July 13, 2009
Date

Hitoshi Kawaguchi
Name: Hitoshi KAWAGUCHI

Each Inventor: Please Sign and Date Below:

July 9, 2009
Date

Kensuke Nakamura
Name: Kensuke NAKAMURA